

October 2008

## FDC5661N\_F085

# N-Channel Logic Level PowerTrench $^{\circledR}$ MOSFET 60V, 4A, 60m $\Omega$

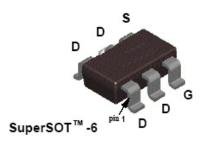
### **Features**

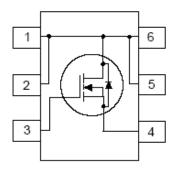
- $\blacksquare$  R<sub>DS(on)</sub> = 47m $\Omega$  at V<sub>GS</sub> = 10V, I<sub>D</sub> = 4.3A
- $\blacksquare$  R<sub>DS(on)</sub> = 60m $\Omega$  at V<sub>GS</sub> = 4.5V, I<sub>D</sub> = 4A
- Typ  $Q_{g(TOT)}$  = 14.5nC at  $V_{GS}$  = 10V
- Low Miller Charge
- Qualified to AEC Q101
- RoHS Compliant

### **Applications**

- DC/DC converter
- Motor Drives







### **MOSFET Maximum Ratings** T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	60	V
$V_{GS}$	Gate to Source Voltage	±20	V
	Drain Current Continuous (V <sub>GS</sub> = 10V)	4.3	۸
'D	Pulsed	20	_ A
$P_{D}$	Power Dissipation	1.6	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature	-55 to +150	°C

### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance Junction to Case	30	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-263, 1in <sup>2</sup> copper pad area	78	°C/W

### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.661N	FDC5661N_F085	SSOT-6	7"	8mm	3000 units

### **Electrical Characteristics** T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Off Cha	racteristics						

B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0V$		60	1	-	٧
	Zero Gate Voltage Drain Current	$V_{DS} = 48V$ ,		-	-	1	
DSS	Zero Gate voltage Drain Current	$V_{GS} = 0V$	$T_A = 150^{\circ}C$	-	-	250	μА
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

### On Characteristics

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1	2.0	3	V
		$I_D = 4.3A, V_{GS} = 10V$	-	38	47	
rno.	Drain to Source On Resistance	I <sub>D</sub> = 4A, V <sub>GS</sub> = 4.5V	-	46	60	mΩ
r <sub>DS(on)</sub>	Brain to Gource on Resistance	$I_D = 4.3A, V_{GS} = 10V$ $T_J = 150^{\circ}C$	-	69	86	11152

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	)/ OF)/ )/	2) (	-	763	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0 f = 1MHz	JV,	-	68	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	- 11VII 12		-	36	-	pF
$R_G$	Gate Resistance	f = 1MHz		-	2.6	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	V <sub>GS</sub> = 0 to 10V	.,	-	14.5	19	nC
Q <sub>gs</sub>	Gate to Source Gate Charge		$V_{DD} = 30V$ $I_{D} = 4.3A$	-	2.4	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		1D 7.0A	-	2.9	-	nC

Units

ns

ns

ns

Max

36

# **Electrical Characteristics** $T_A = 25^{\circ}C$ unless otherwise noted

**Parameter** 

Switc	ching Characteristics					
t <sub>on</sub>	Turn-On Time		-	-	17.6	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	7.2	-	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 30V, I_D = 4.3A$	-	1.6	-	ns
t	Turn Off Dolay Timo	$V_{GS}$ = 10V, $R_{GS}$ = $6\Omega$		10.3		nc

**Test Conditions** 

Min

Тур

19.3

3.1

### **Drain-Source Diode Characteristics**

Turn-Off Delay Time

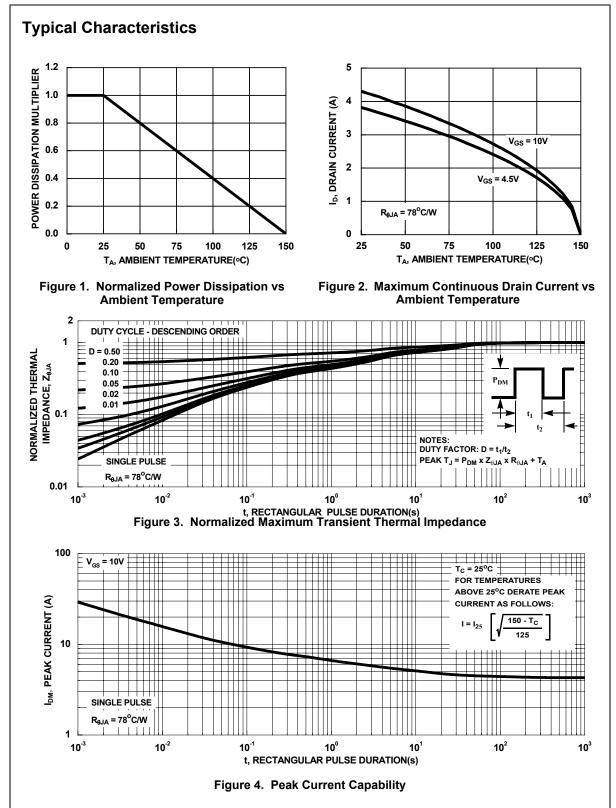
Fall Time

Turn-Off Time

Symbol

V	Source to Drain Diode Voltage	I <sub>SD</sub> = 4.3A	-	0.8	1.25	\/
$V_{SD}$	Source to Drain blode voltage	I <sub>SD</sub> = 2.1A	-	0.8	1.0	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> = 4.3A, dI <sub>SD</sub> /dt = 100A/μs	-	18.4	24	ns
Q <sub>rr</sub>	Reverse Recovery Charge	i <sub>SD</sub> = 4.3A, di <sub>SD</sub> /dt = 100A/μS	1	10.0	13	nC

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.



### **Typical Characteristics**

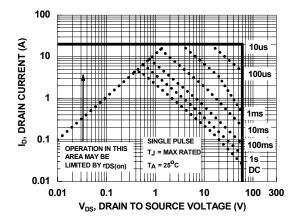


Figure 5. Forward Bias Safe Operating Area

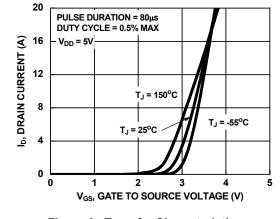


Figure 6. Transfer Characteristics

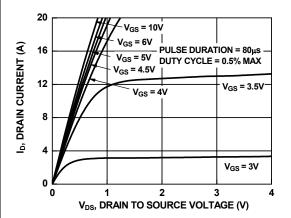


Figure 7. Saturation Characteristics

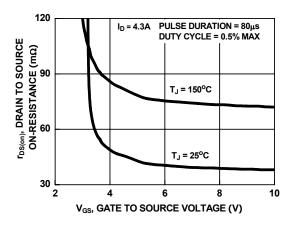


Figure 8. Drain to Source On-Resistance Variation vs Gate to Source Voltage

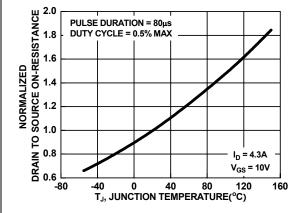


Figure 9. Normalized Drain to Source On Resistance vs Junction Temperature

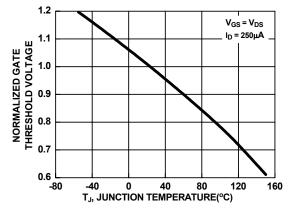


Figure 10. Normalized Gate Threshold Voltage vs Junction Temperature

### **Typical Characteristics**

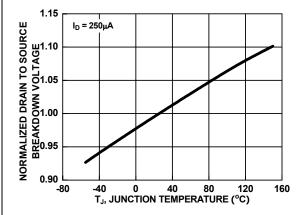


Figure 11. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

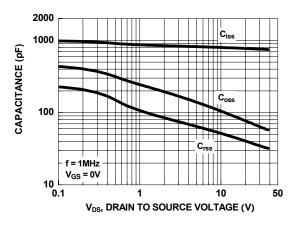


Figure 12. Capacitance vs Drain to Source Voltage

Figure 14.

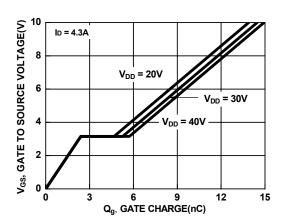


Figure 13. Gate Charge vs Gate to Source Voltage





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